

SPECIFICATION FOR TFT MODULE

MODULE NO: YB-TG480800S18A-N-A0

Doc.Version:00

Customer Approval:

<input type="checkbox"/> Accept	<input type="checkbox"/> Reject
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YEEBO	NAME	SIGNATURE	DATE
Prepare	Electronic Engineer	黄松	2025-03-12
Check	Mechanical Engineer		
Verify			
Approval		孙五南	2025/3/12

■ APPROVAL FOR SPECIFICATIONS ONLY

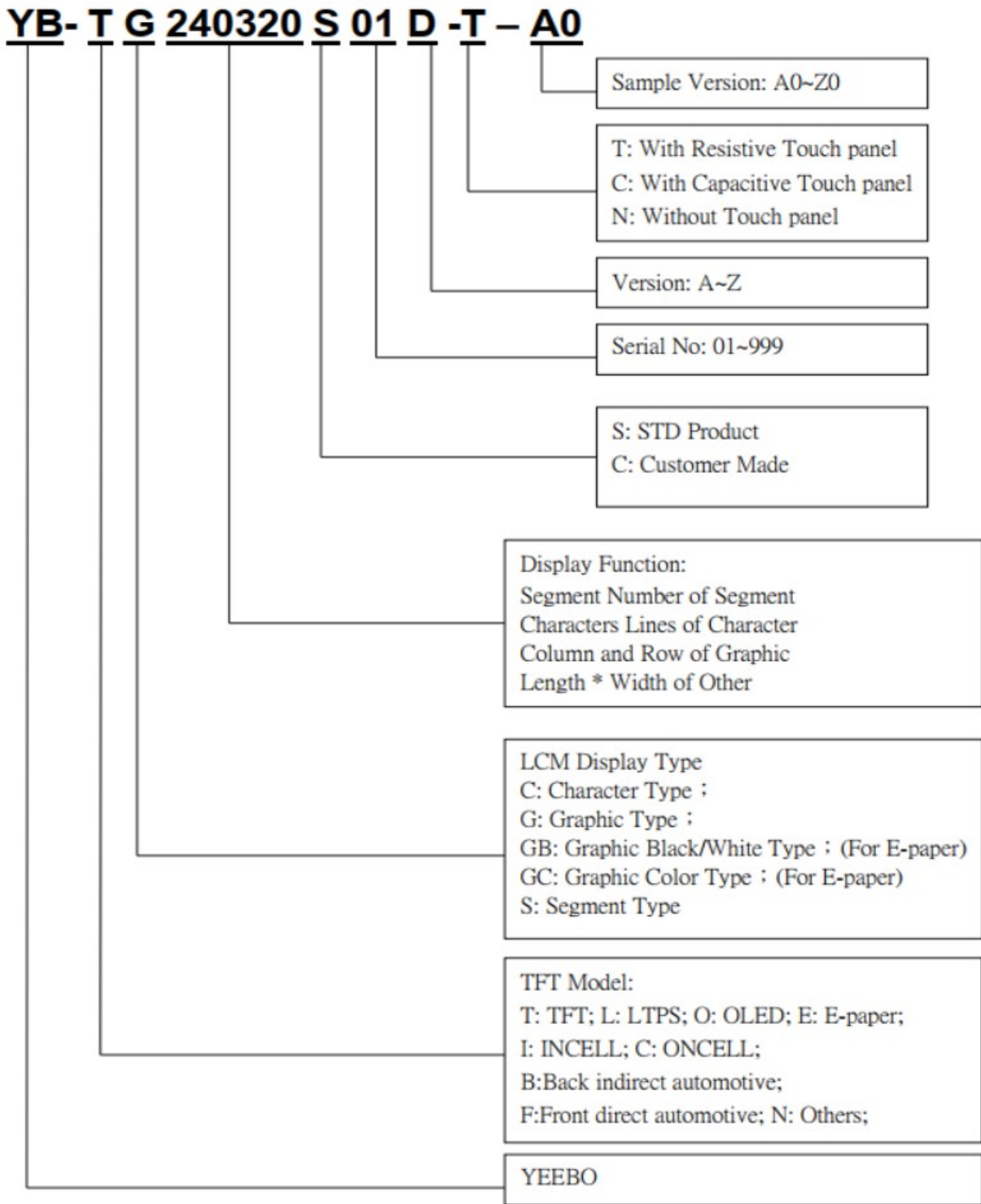
APPROVAL FOR SPECIFICATIONS AND SAMPLE

WIMRD005-02-D

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3. Module Numbering System:
(Example)



4. General Specification:

ITEM	CONTENTS
Module Size	56.74 (W) * 97.00 (H) * 2.0 (T) mm
Module Size(With FPC)	65.54 (W) * 121.43 (H) * 2.0 (T) mm
Display Size(Diagonal)	3.97 inch
Display Format	480(RGB) * 800 Pixels
Active Area	51.84 (W) * 86.4 (H) mm
Pixel Pitch	0.108*0.108 mm
LCD Type	16.7M Color / Transmissive / Normal Black
View Direction	Free
Controller IC	ST7701P
Weight	TBD

6. Electrical Characteristics

6-1 Absolute Maximum Ratings

(Ta=25°C)

Parameter	Symbol	Min.	Max.	Unit	Remarks
LC operating Voltage ^[1]	V _{OP}		5.0	V	Ta=25+/-2°C
Operating Temperature (Humidity)	T _{OP}	-20	+70	°C	
	RH		90	%	At 60°C
Storage Temperature (Humidity)	T _{ST}	-30	+80	°C	
	RH		90	%	At 60°C

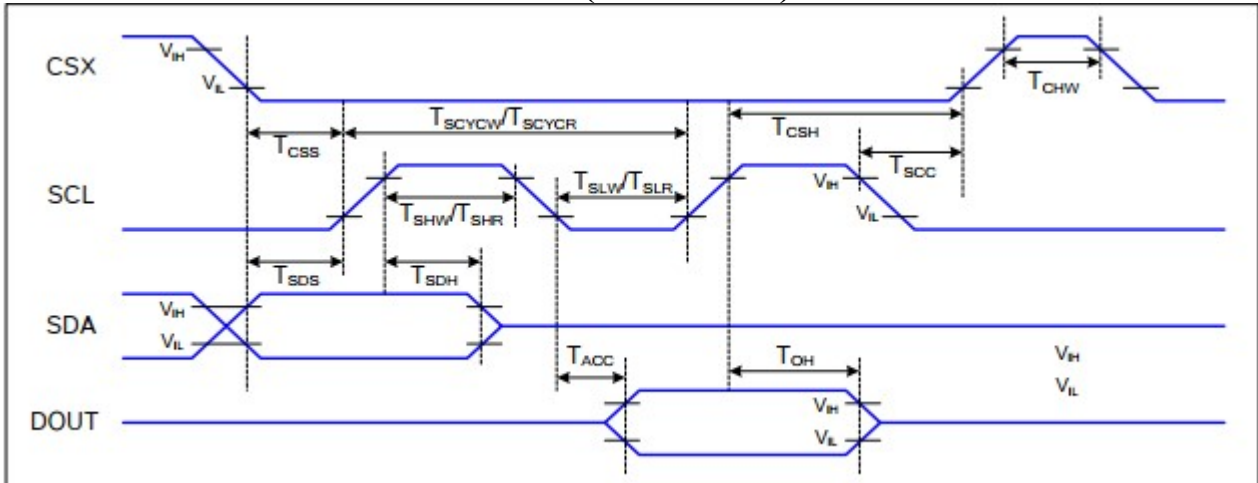
6-2 Operating Conditions

(Ta=25°C)

Item	Symbol	Condition	Min.	Type	Max.	Unit	Remark
Power Supply Voltage	V _{DD}	-	2.5	2.8	4.8	V	
Supply Voltage(Logic)	V _{DDI}	-	1.68	2.8	3.3	V	
IO Supply Voltage	V _{IH}	-	0.7 V _{DDI}	-	V _{DDI}	V	
	V _{IL}	-	V _{SS}	-	0.3 V _{DDI}	V	
	V _{OH}	-	0.8 V _{DDI}	-	V _{DDI}	mA	
	V _{OL}	-	V _{SS}	-	0.2 V _{DDI}	V	
Power Supply Current	I _{DD}	V _{DD} =2.8V	-	TBD	-	mA	

6-3 AC Characteristics

Serial Interface Characteristics (3-line serial):



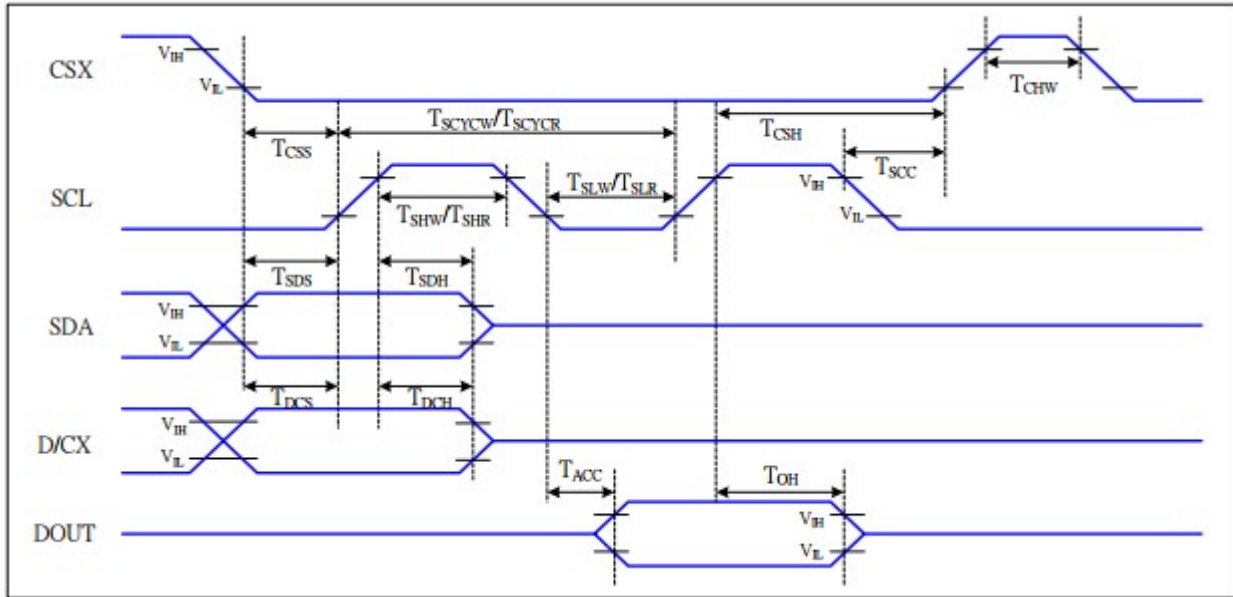
3-line serial interface timing characteristics

V_{DDI}=1.8V, V_{DD}=2.8V, AGND=DGND=0V, T_a=25°C

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	60		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
SCL	T _{SCYC_W}	Serial clock cycle (Write)	66		ns	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	
	T _{SLW}	SCL "L" pulse width (Write)	15		ns	
	T _{SCYC_R}	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T _{SDS}	Data setup time	10		ns	
	T _{SDH}	Data hold time	10		ns	
SDO (DOUT)	T _{ACC}	Access time	20	50	ns	Max: CL=30pF
	T _{OH}	Output disable time	50	50	ns	Min: CL=8pF

3-line serial interface timing characteristics

Serial Interface Characteristics (4-line serial):



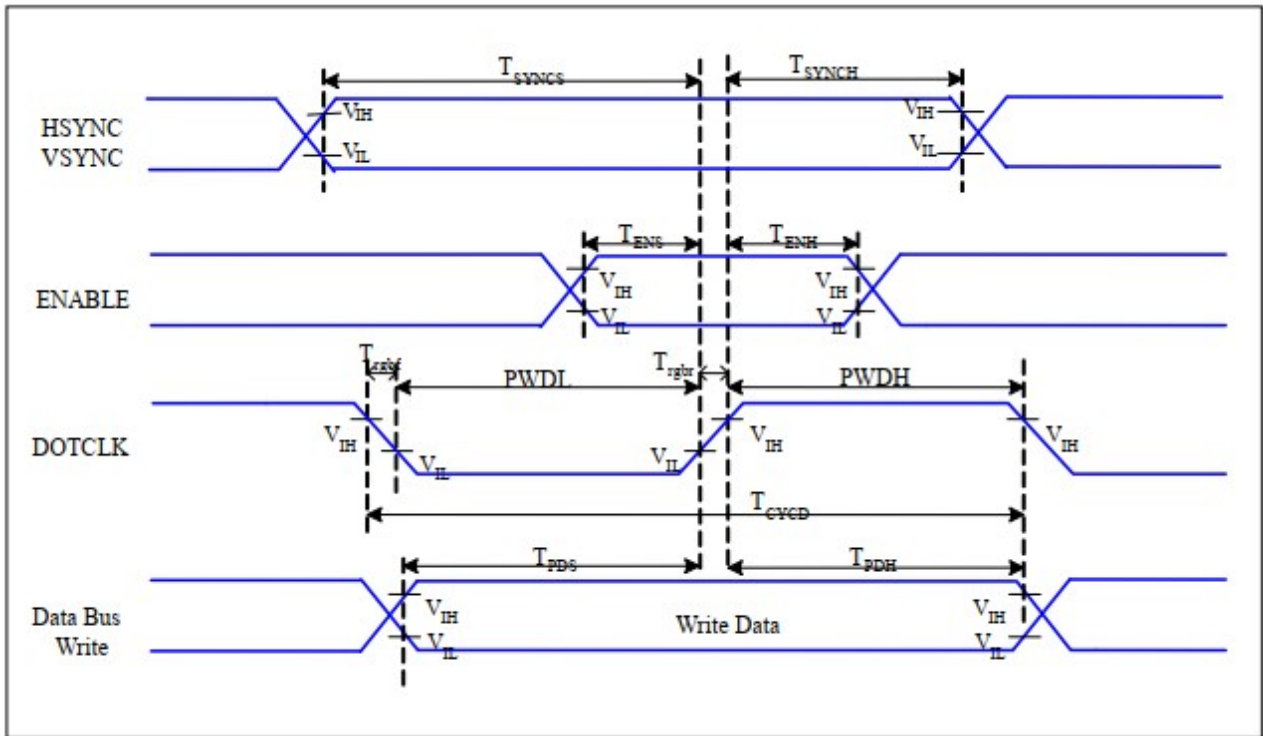
4-line serial interface timing characteristics

VDDI=1.8V, VDD=2.8V, AGND=DGND=0V, Ta=25 °C

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	-write command
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	-read command
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
D/CX	T_{DCS}	D/CX setup time	10		ns	
	T_{DCH}	D/CX hold time	10		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	
SDO (DOUT)	T_{ACC}	Access time	20	50	ns	Max: CL=30pF Min: CL=8pF
	T_{OH}	Output disable time	50	50	ns	

4-line serial interface timing characteristics

Serial Interface Characteristics (RGB):



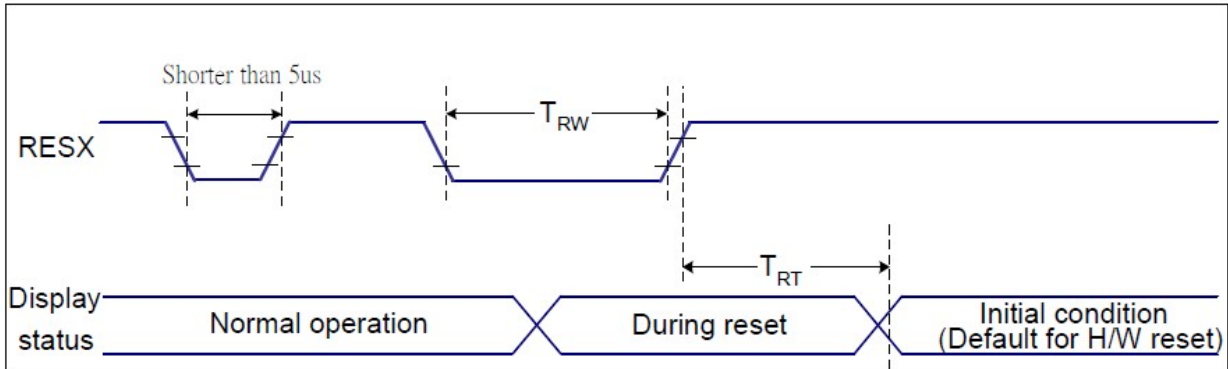
RGB interface timing characteristics

VDDI=1.8V, VDD=2.8V, AGND=DGND=0V, Ta=25 °C

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYNC, HSYNC Setup Time	5	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	5	-	ns	
	T_{ENH}	Enable Hold Time	5	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	15	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	15	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	33	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	15	ns	
DB	T_{PDS}	PD Data Setup Time	5	-	ns	
	T_{PDH}	PD Data Hold Time	5	-	ns	

RGB interface timing characteristics

Reset Timing



VDDI=1.8, VDD=2.8, AGND=DGND=0V, Ta=25 °C

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
			120 (Note 1, 6, 7)	ms	

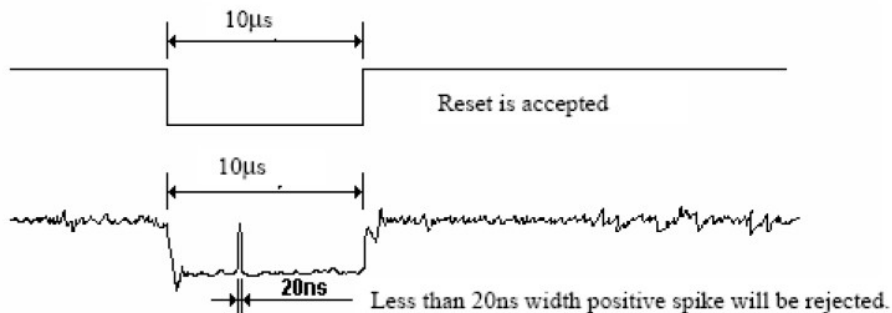
Notes:

1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (t_{RT}) within 5 ms after a rising edge of RESX.
2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.
6. When Reset applied during Sleep Out Mode.
7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

Power ON/OFF Sequence

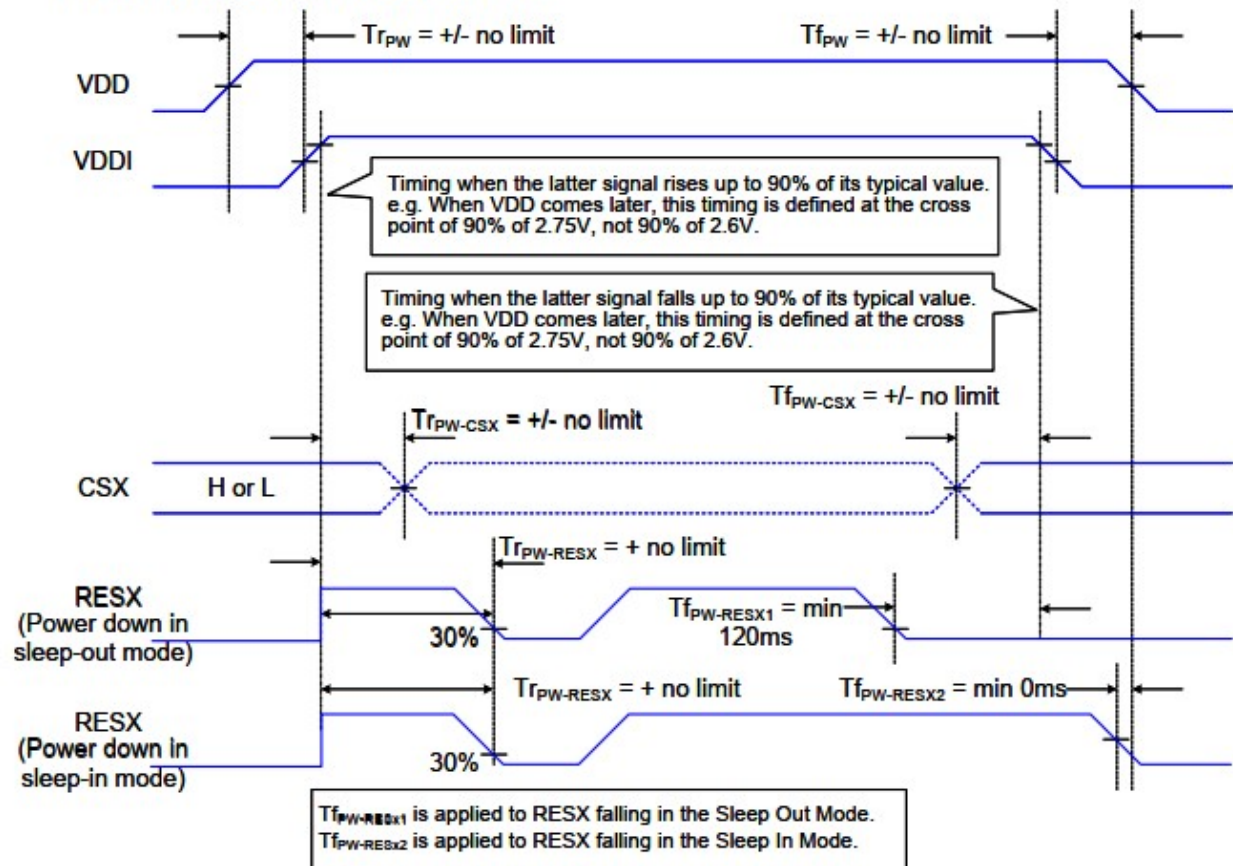
VDDI and VDDA can be applied or powered down in any order. During the Power Off sequence, if the LCD is in the Sleep Out mode, VDDA and VDDI must be powered down with minimum 120msec. If the LCD is in the Sleep In mode, VDDA and VDDI can be powered down with minimum 0msec after the RESX is released.

CSX can be applied at any timing or can be permanently grounded. RESX has high priority over CSX.

Notes:

1. There will be no damage to the ST7701P if the power sequences are not met.
2. There will be no abnormal visible effects on the display panel during the Power On/Off Sequences.
3. There will be no abnormal visible effects on the display between the end of Power On Sequence and before receiving the Sleep Out command, and also between receiving the Sleep In command and the Power Off Sequence.
4. If the RESX line is not steadily held by the host during the Power On Sequence as defined in Sections 9.1, then it will be necessary to apply the Hardware Reset (RESX) after the completion of the Host Power On Sequence to ensure correct operations. Otherwise, all the functions are not guaranteed.
5. When VDDA is in power off State, the MIPI must set in Ultra Low Power Mode (GND Level).

The power on/off sequence is illustrated below



7. Optical Characteristics:

Item	Symbol	Conditions	Specifications			Unit	Note	
			Min	Typ	Max			
Transmittance	T(%)	-	3.34	3.93	-	-	-	
Contrast Ratio	CR	$\theta=0^\circ$	550	800	-		(1) (2)	
Response time	TR+TF	Normal Viewing Angle	-	35	-	ms	(1) (3)	
NTSC	-	-	-	70	-	%	Note 1	
Viewing Angle	Hor.	θ_{x+}	$CR \geq 10$	80	85	-	deg.	(1)
		θ_{x-}		80	85	-		
	Ver.	θ_{y+}		80	85	-		
		θ_{y-}		80	85	-		

Measuring Condition

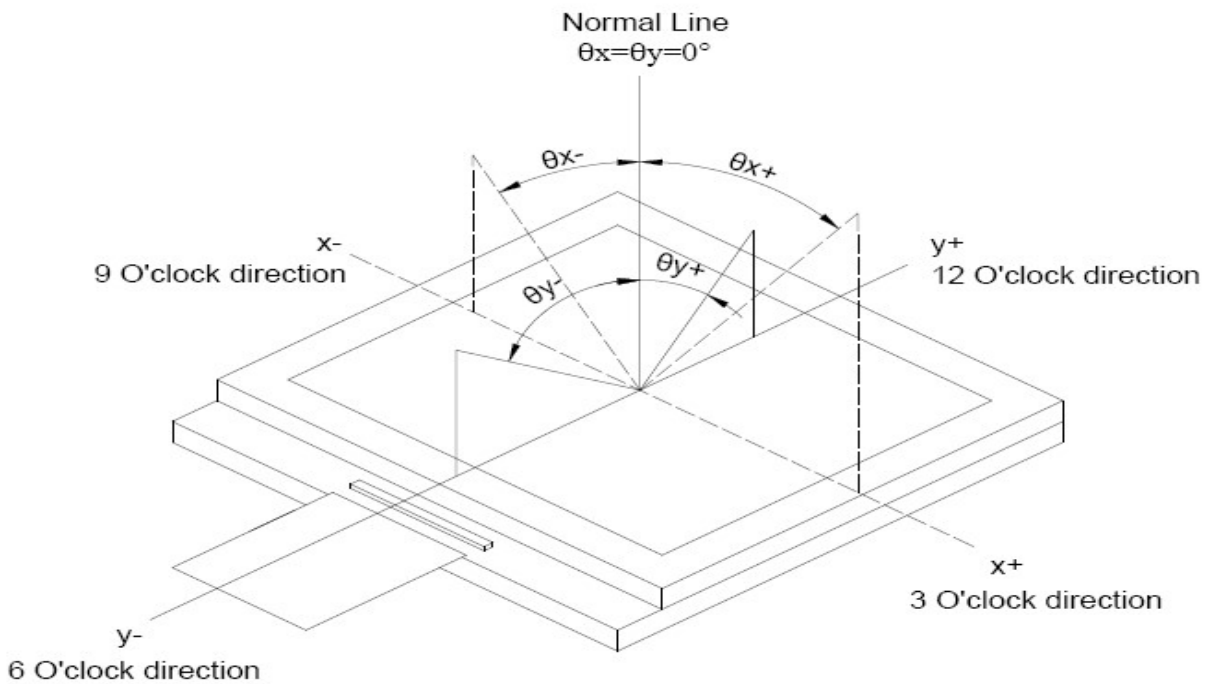
1. Measuring surrounding: dark room
2. Ambient temperature: $25 \pm 2^\circ\text{C}$
3. 30 min. Warm-up time.

Color of CIE Coordinate:

($T_a=25^\circ\text{C}$)

Item	Symbol	Condition	Min.	Typ.	Max.	
Chromaticity Coordinates (Transmissive)	Red	x	-	0.647	-	
		y	-	0.317	-	
	Green	x	$\theta = \varphi = 0^\circ$ LED Backlight	-	0.275	-
		y		-	0.582	-
	Blue	x		-	0.140	-
		y		-	0.088	-
	White	x		-	0.310	-
		y		-	0.336	-

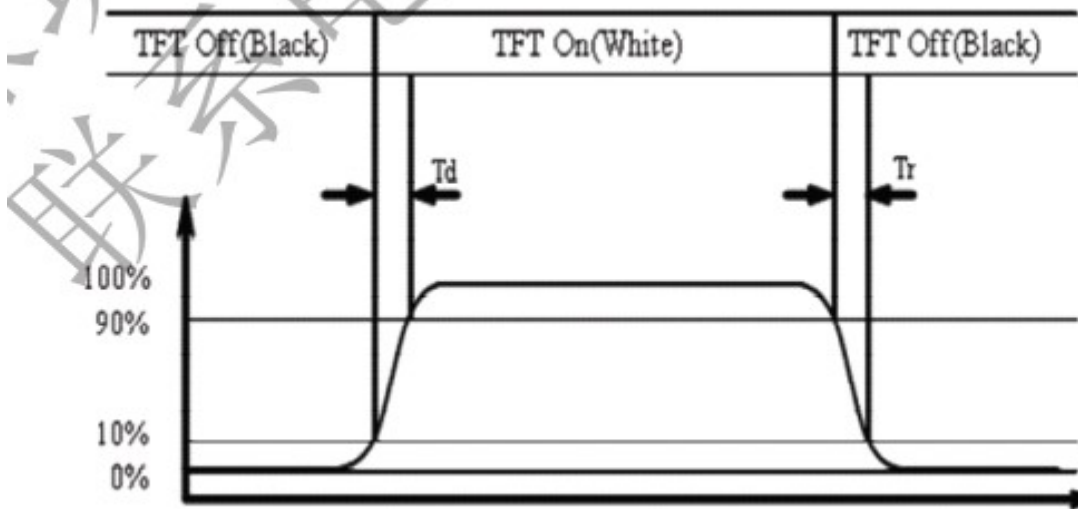
Note (1) Definition of Viewing Angle :



Note (2) Definition of Contrast Ratio(CR) :
measured at the center point of panel

$$\text{Contrast ratio (CR)} = \frac{\text{Photo detector output when LCD is at "White" state}}{\text{Photo detector output when LCD is at "Black" state}}$$

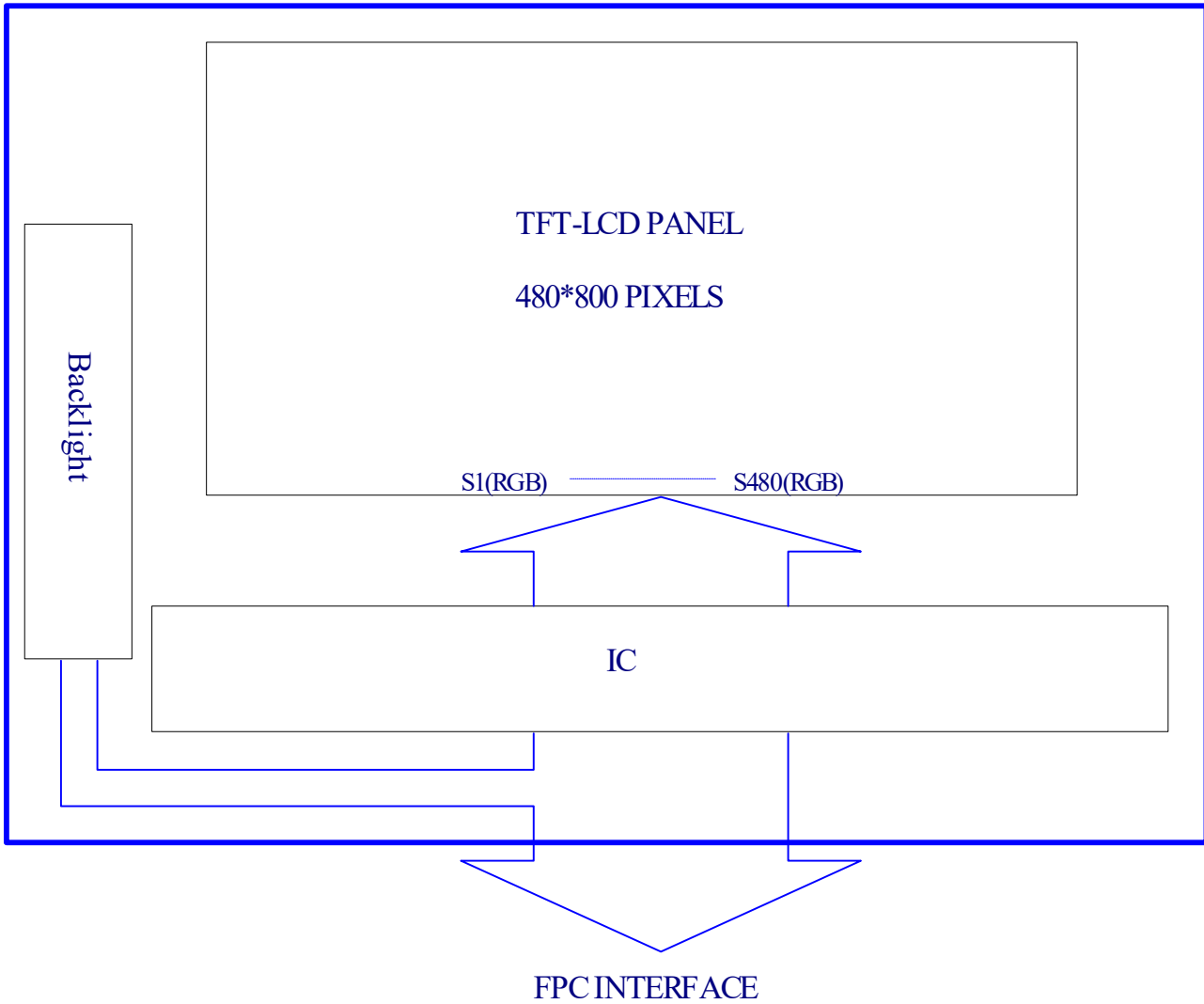
Note (3) Definition of Response Time : Sum of TR and TF



No.	Symbol	Function					Remark
1	LED_K	LED cathode					
2	LED_A	LED anode					
3	NC	Not connect.					
4	NC	Not connect.					
5	NC	Not connect.					
6	NC	Not connect.					
7	VDD	Power Supply for analog Voltage					
8	VDDI	Power Supply for logic Voltage					
9	IM3	IM3	IM2	IM1	IM0	MPU Interface Mode	
10	IM2	0	0	1	1	RGB+16b_SPI(rise)	
11	IM1	1	0	0	1	RGB+8b_SPI(rise)	
12	IM0	1	0	1	0	RGB+9b_SPI(rise)	
		1	0	1	1	RGB+16b_SPI(fall)	
13	SDO	Serial data output pin used the for SPI interface					
14	SDA	Serial data input/output bidirectional pin for SPI interface Serial input data for I2C interface.					
15	DCX	Data /command select pin. The SPI interface (DCX): The signal for command or parameter select. Low: Command High: Parameter					
16	SCL	Write enable clock input pin Serial clock input for SPI interface. Serial input clock for I2C interface.					
17	NC	Not connect					
18	CSX	Chip select input pin Low: the chip is selected and accessible High: the chip is not selected and not accessible.					
19	RESX	Reset pin					
20	DB23	Data bus					
21	DB22	Data bus					
22	DB21	Data bus					
23	DB20	Data bus					
24	DB19	Data bus					
25	DB18	Data bus					
26	DB17	Data bus					
27	DB16	Data bus					
28	DB15	Data bus					
29	DB14	Data bus					
30	DB13	Data bus					
31	DB12	Data bus					
32	DB11	Data bus					
33	DB10	Data bus					
34	DB9	Data bus					
35	DB8	Data bus					

No.	Symbol	Function	Remark
36	DB7	Data bus	
37	DB6	Data bus	
38	DB5	Data bus	
39	DB4	Data bus	
40	DB3	Data bus	
41	DB2	Data bus	
42	DB1	Data bus	
43	DB0	Data bus	
44	DE	Data enable signal in RGB interface.	
45	GND	Ground	
46	PCLK	RGB clock	
47	GND	Ground	
48	HS	Horizontal synchronizing signal in RGB interface.	
49	VS	Vertical synchronizing signal in RGB interface.	
50	TE	Tearing effect pin	
51	LED_PWM	Backlight control	

9. Block Diagram:



10. Backlight:

1. Standard Lamp Styles (Edge Lighting Type):
The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted.
By a resistor or a potentiometer.

3. Data About LED Backlight:

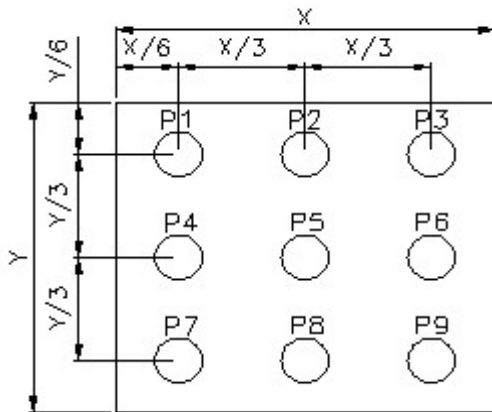
(Ta=25°C)

PARAMETER	Sym.	Min.	Typ.	Max.	Unit	Test Condition	Note
Supply Current	I	-	20	-	mA	V=26.4V	
Supply Voltage	V	22.4	26.4	27.2	V	If=20mA	
Luminous Intensity for LCM	IV	300	350	-	cd/m ²		2
Uniformity for LCM	-	80	-	-	%		3
Life Time	-	20000	-	-	Hr.		4
Color	White						

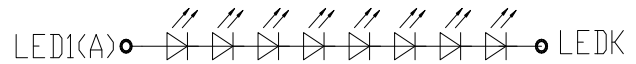
NOTE:

1. Backlight Only
2. Average Luminous Intensity of P1-P9
3. Uniformity = Min/Max * 100%
4. LED life time defined as follows: The final brightness is at 50% of original brightness

Measured Method: (X*Y: Light Area)



Internal Circuit Diagram



LED CIRCUIT DIAGRAM

(Effective spatial Distribution)

Using aperture of 1°, distance 50cm

11. Standard Specification for Reliability:

11-1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 240 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 240 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -20°C for 30 minutes → normal temperature for 5 minutes → +60°C for 30 minutes → normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static Discharge	Air: ±4KV 150pF/330Ω 5 times
		Contact: ±2KV 150pF/330Ω 5 time

*Sample size for each test item is 3~5pcs



11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11.2, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11- 3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±5°C), normal humidity (50±10% RH), and in area not exposed to direct sun light.
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12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

(i) Test method: According to **ISO2859-1**.General Inspection Level II take a single time.

(ii) The defects classify of AQL as following:

Major defect: AQL =0.65

Minor defect: AQL =2.5

Total defects: AQL =2.5

12-3. Non- conforming Analysis & Deal with Manners

a. Non- conforming Analysis:

(i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.

(ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.

(iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.

b. Disposition of non- conforming:

(i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.

(ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

12-4. Agreement items

Both sides should discuss together when the following problems happen.

a. There is any problem of standard of quality assurance, and both sides should think that must be modified.

b. There is any argument item which does not record in the standard of quality assurance.

c. Any other special problem.

12-5. Standard of the Product Appearance Test

a. Manner of appearance test:

(i) Illumination: External Appearance Inspection : 1000 ± 200 Lux ; Light on inspection : 200 ± 50 Lux.

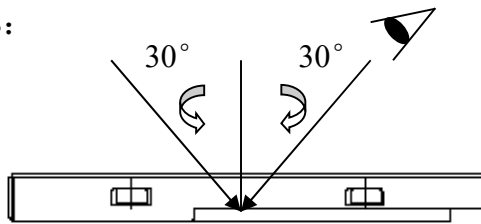
(ii) To be a distance about 30 ± 5 cm in front of LCD unit, viewing line should be perpendicular to the surface of the module judge the visual appearance with human's eyes.

(iii) Scope of inspection perspective:

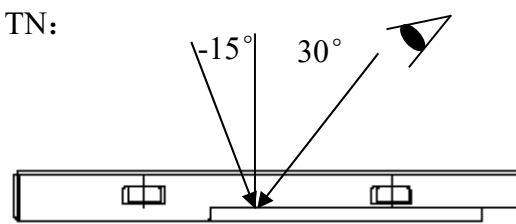
The inspection angle of IPS screen is within $\pm 30^\circ$ of the vertical line on the product surface; The TN screen inspection angle is -15° from the vertical line of the product surface in the 12 o'clock direction to 30° from the vertical line of the product surface in the 6 o'clock direction.

(iii) Temperature: $25 \pm 5^\circ\text{C}$ Humidity: $60 \pm 10\% \text{RH}$

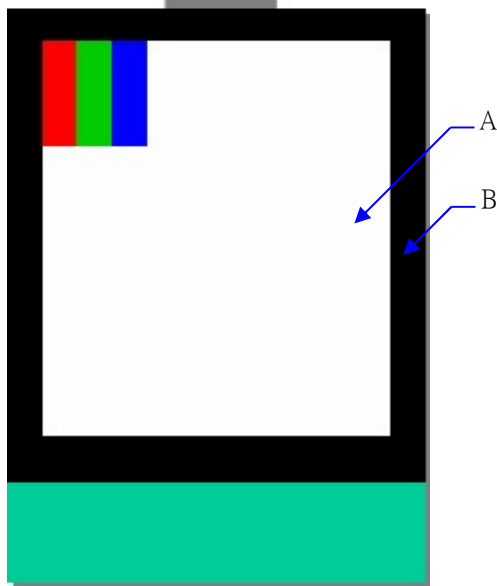
IPS:



TN:



(iv) Definition of area:



A. Area: Viewing area.

B. Area: Out of viewing area.
(Outside viewing area)

b. Basic principle:

(i) It will accord to the AQL when the standard cannot be described.

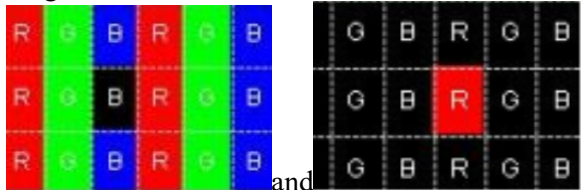
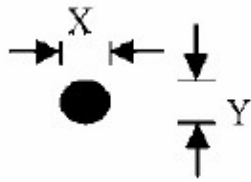
(ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.

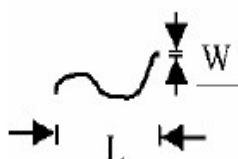
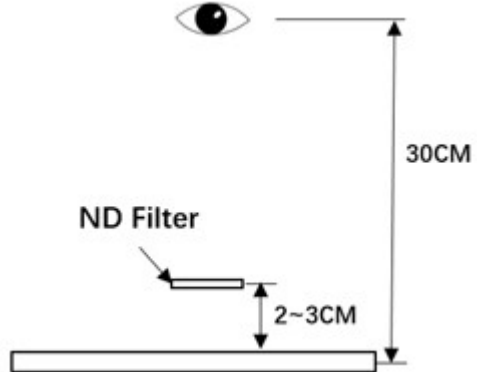
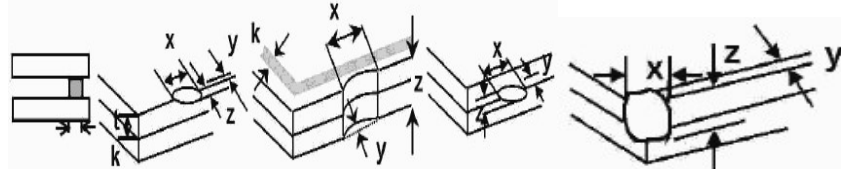
(iii) Must add new item on time when it is necessary.

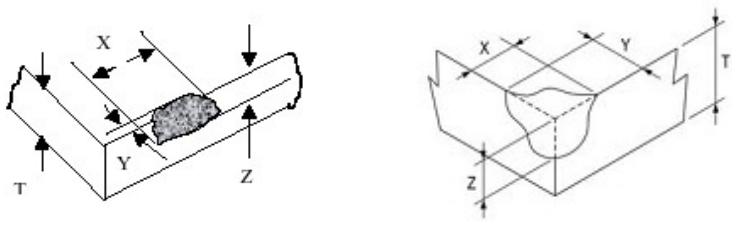
c. Standard of inspection: (Unit: mm)

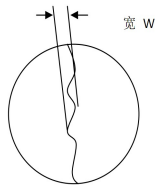
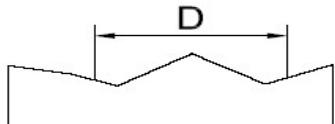
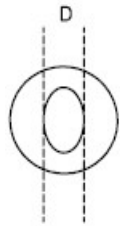
12-6. Inspection specification

Defect out of viewing area can be neglected.

NO	Item	Criterion	AQL														
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types.	0.65														
02	Pixel Defect	Bright and Black dot define:  Pixel Defect as below drawing: <table border="1"> <thead> <tr> <th>Type</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>Bright Dot</td> <td>$N \leq 1$</td> </tr> <tr> <td>Two bright dots</td> <td>$N \leq 0$</td> </tr> <tr> <td>Dark Dot</td> <td>$N \leq 2$</td> </tr> <tr> <td>Two Dark dots</td> <td>$N \leq 0$</td> </tr> <tr> <td>Three Dark dots</td> <td>$N \leq 0$</td> </tr> <tr> <td>Total(Bright+Dark dot)</td> <td>$N \leq 2$</td> </tr> </tbody> </table> *Densely spaced: No more than two spots within 10mm.	Type	Acceptable Q'ty	Bright Dot	$N \leq 1$	Two bright dots	$N \leq 0$	Dark Dot	$N \leq 2$	Two Dark dots	$N \leq 0$	Three Dark dots	$N \leq 0$	Total(Bright+Dark dot)	$N \leq 2$	2.5
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03	LCD , Touch Panel and Backlight Black and white spots/lines contamination (Foreign Material)	3.1 Dot type: As following drawing $\Phi = (X+Y) / 2$  <table border="1"> <thead> <tr> <th>Size(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.10$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.10 < \Phi \leq 0.30$</td> <td>2</td> </tr> <tr> <td>$0.30 < \Phi$</td> <td>0</td> </tr> </tbody> </table> 3.1.1 Not visible through 5% ND filter 3.1.2 Densely spaced: No more than two spots within 5mm. 3.1.3 This is acceptable when surface dirt can be removed by wiping.	Size(mm)	Acceptable Q'ty	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.30$	2	$0.30 < \Phi$	0	2.5						
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$\Phi \leq 0.10$	Accept no dense																
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$0.30 < \Phi$	0																
		3.2 Tiny bright dot、Dense tiny highlights: Definition of Tiny bright dot: $\Phi < 0.10\text{mm}$; Ignore, clustered is not allowed($N \leq 5, D \leq 5$) *Not visible through 5% ND filter	2.5														

NO	Item	Criterion	AQL												
03	LCD ,Touch Panel and Backlight Black and white spots/lines contamination(Foreign Material)	3.3 Line type: (As following drawing)  <table border="1" data-bbox="750 268 1324 481"> <thead> <tr> <th>Length(mm)</th> <th>Width(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>---</td> <td>$W \leq 0.03$</td> <td>Accept no dense</td> </tr> <tr> <td>$L \leq 5.0$</td> <td>$0.03 < W \leq 0.075$</td> <td>2</td> </tr> <tr> <td>---</td> <td>$0.075 < W$</td> <td>Rejection</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two spots within 5mm.</p>	Length(mm)	Width(mm)	Acceptable Q'ty	---	$W \leq 0.03$	Accept no dense	$L \leq 5.0$	$0.03 < W \leq 0.075$	2	---	$0.075 < W$	Rejection	2.5
Length(mm)	Width(mm)	Acceptable Q'ty													
---	$W \leq 0.03$	Accept no dense													
$L \leq 5.0$	$0.03 < W \leq 0.075$	2													
---	$0.075 < W$	Rejection													
04	Polarizer bubbles	If bubbles are visible, Judge using black spot specifications, not easy to find, must check in specify direction. <table border="1" data-bbox="790 638 1324 806"> <thead> <tr> <th>Size Φ(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.15$</td> <td>ignored (Dense NG)</td> </tr> <tr> <td>$0.15 < \Phi \leq 1.00$</td> <td>2</td> </tr> <tr> <td>$1.00 < \Phi$</td> <td>0</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two spots within 5mm. * Outside of the V.A. is disregard.</p>	Size Φ (mm)	Acceptable Q'ty	$\Phi \leq 0.15$	ignored (Dense NG)	$0.15 < \Phi \leq 1.00$	2	$1.00 < \Phi$	0	2.5				
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$\Phi \leq 0.15$	ignored (Dense NG)														
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05	Mura	Not visible through 5% ND filter.  <p>*ND card is 2~3cm from the panel, human eye is 30±5cm from the panel; The line of sight is moved to the ND card for judgment: if it is not visible for 2-3 seconds - OK, visible - NG</p>	2.5												
06	Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Single-layer glass thickness a: LCD side length L: Electrode pad length 8.1 Chip on panel surface and crack between panels and Corner crack:  <table border="1" data-bbox="375 1713 1197 1836"> <tbody> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$z \leq t$</td> <td>Not over BM glue area</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip. ⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and do not affect the function.</p>	z: Chip thickness	y: Chip width	x: Chip length	$z \leq t$	Not over BM glue area	$x \leq 1/8a$	2.5						
z: Chip thickness	y: Chip width	x: Chip length													
$z \leq t$	Not over BM glue area	$x \leq 1/8a$													
NO	Item	Criterion	AQL												

07	Scratches	Follow NO.3 -3 Line Type.	2.5								
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5								
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	2.5 2.5 0.65								
10	Bezel	Bezel must comply with product specifications.	2.5								
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 11.7 PCBA cosmetic control base on latest IPC standard, IPC-A-610, acceptalbe limit of grade 2.	2.5 2.5 2.5 2.5 0.65 0.65 2.5								
12	FPC	Affect function rejection, do not affect function acceptance.	2.5								
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	2.5 0.65								
14	Touch Panel Chipped glass	Edge breakage can't affect visual effection (edge breakage can't cause damage to circuit); over lens have no visual damage 	2.5								
		<table border="1"> <thead> <tr> <th>x: Chip length</th> <th>y: Chip width</th> <th>z: Chip thickness</th> <th>Acceptable numbers</th> </tr> </thead> <tbody> <tr> <td>$x \leq 1\text{mm}$</td> <td>$Y \leq 0.5\text{mm}$</td> <td>$z \leq t$</td> <td>2</td> </tr> </tbody> </table>	x: Chip length	y: Chip width	z: Chip thickness	Acceptable numbers	$x \leq 1\text{mm}$	$Y \leq 0.5\text{mm}$	$z \leq t$	2	
x: Chip length	y: Chip width	z: Chip thickness	Acceptable numbers								
$x \leq 1\text{mm}$	$Y \leq 0.5\text{mm}$	$z \leq t$	2								
NO	Item	Criterion	AQL								

15	V/A printed edges sawtooth inspected according to this standard LOGO's sawtooth	Some contentious defect judged according to samples.			2.5								
		Product type	Conditions										
		Same size	1、width below 0.2mm (included) ignored, above 0.2mm NG 2、 Length not accounted										
16	Touch Panel(Fish eye、dent and bubble on film)	<table border="1"> <thead> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.2$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.2 < D \leq 0.40$</td> <td>2</td> </tr> <tr> <td>$0.40 < D$</td> <td>0</td> </tr> </tbody> </table>		SIZE(mm)	Acceptable Q'ty	$\Phi \leq 0.2$	Accept no dense	$0.2 < D \leq 0.40$	2	$0.40 < D$	0	 	2.5
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17	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion ($\leq 2.5\%$), it is acceptable.		2.5									
18	Touch Panel Linearity	Less than 2.5% is acceptable.		2.5									
19	LCD Ripple	Touch the touch panel, cannot see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g		2.5									
20	General appearance	20.1 Product packaging must the same as specified on packaging specification sheet.		0.65									
		20.2 Product dimension and structure must conform to product Specification sheet.		0.65									

13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. When the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of $25\pm 10^{\circ}\text{C}$, and in a relative humidity of $50\pm 10\%\text{RH}$. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than $310\pm 10^{\circ}\text{C}$ and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Warranty

This product has been manufactured to specifications as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we will not take responsibility if the product is used in medical devices, nuclear power control equipment, aerospace equipment, fire and security systems, or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required. If the product is to be used in any of the above applications, we will need to enter into a separate product liability agreement.

1. We cannot accept responsibility for any defect arise after additional process of the product (Including disassembly and reassembly), after product delivery.
2. We cannot accept responsibility for any defect, which may arise after the application of strong External force to the product.
3. We cannot accept responsibility for any defect, which may arise due to the application of static Electricity after the product has passed your company's acceptance inspection procedures.
4. We cannot accept responsibility for industrial property, which may arise through the use of your product, with exception to those issues relating directly to the structure or method of manufacturing of our product within one year from YEEBO shipment.
5. For Heatseal Product which required to heatseal by customer side, parts must be used within three months after delivery from factory.
6. For TAB Product which required to solder by customer side, parts must be used within three Months after delivery from factory.
7. The liability of YB is limited to repair or replacement on the terms set forth below. YB will not be responsible for any subsequent or consequential events or injury or damage to any personnel or user including third party personnel and/or user. Unless otherwise agreed in writing between YB and the customer, YB will only replace or repair any of its LCD which is found defective electrically or visually when inspected in accordance with YB GENERAL LCD INSPECTION STANDARD.

15. Guarantee:

Our products meet requirements of the environment.

YEEBO ROHS requirement is based on European Union Directive 2011/65/EU (ROHS) Requirements and Update.